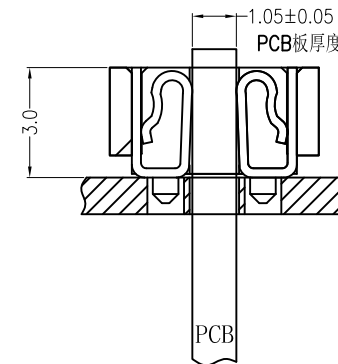


Board Layout

REV	ECN No.	DESCRIPTION	DESIGN	DATE
A1		Release	吴丹平	2015.01.23
A3		基板材质PA9T变更为LCP	蒋建银	2018.08.13
A4		改善插座导向	蒋建银	2018.09.12
A5		改善簧片接触可靠性	曾令青	2019.07.17



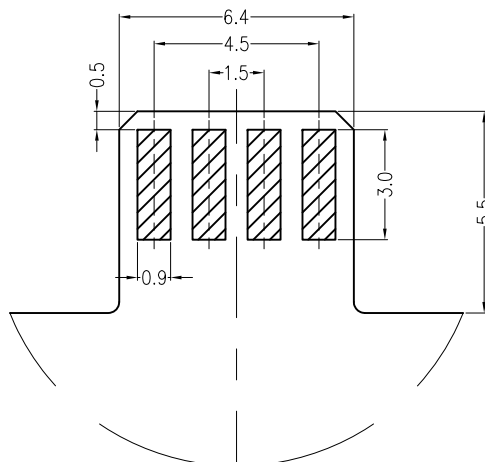
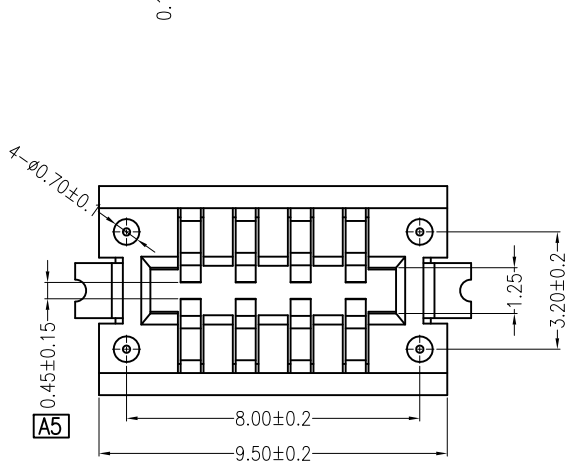
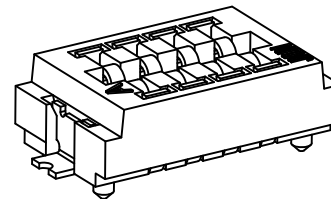
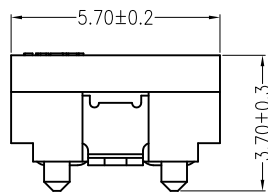
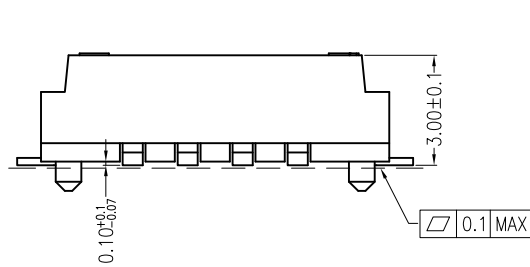
Assembly Layout

主要技术参数 Main Specifications

- 线数 (Poles): 02 to 12
- 接触电阻 (Contact resistance): $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance): $\geq 1000M\Omega$
- 额定电压 (Rated voltage): 125V AC DC
- 额定电流 (Rated current): 1.0A AC DC
- 耐电压 (Withstand Voltage): 800V AC/minute
- 温度范围 (Temperature Range): $-40^{\circ}C \sim +110^{\circ}C$

ORDER INFORMATION:

L029-08-F4MB1-*	
PART No. _____	PACKAGING: P=PE G=TUBE R=REEL
No. FOR CIRCUITS: _____	Metal code: 1=PhosphorBronze
PLASTIC MATERIAL: _____	PLATING: B=MATTE Sn
F4M=LCP (BEIGE)	



Mating PCB detail

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	SOLDER TAB	2 PCS	PhosphorBronze	MATTE Sn-plated
B	CONTACT	8 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

JKUN 温州健坤接插件有限公司
WENZHOU JKUN CONNECTOR CO., LTD.

TITLE: -
1.5mmPITCH 180°WAFER SMT TYPE

X.±0.5	X.±5'	USE: CUSTOMER	PART NO.:	
.X±0.3	.X±2'		L029-08-F4MB1-*	
.XX±0.25	.XX±1'	APPD: 邵敬和	DWG NO.:	
--	--	CHKD: 田峰	JKUN/GCCP-0053	
⊕	◁	DR: 蒋建银	SCALE 1 : 1	SHEET 1 / 1